

REMARKS

The Office Action dated September 21, 2005, has been received and carefully noted. The following remarks are submitted as a full and complete response thereto.

Claims 1, 5 and 7 have been amended. Claims 2, 4 and 6 have been canceled. Therefore, claims 1, 3, 5, and 7 are pending in the present application. Claim 8 has been withdrawn from consideration.

Rejection of Claims 1-2 Under 35 U.S.C. § 102(e)

Claims 1-2 were rejected under 35 U.S.C. § 102(e) as being unpatentable over Huang (U.S. Patent No. 6,777,819). Claim 1 has been amended and claim 2 has been canceled. To the extent it is still relevant, this rejection is respectfully traversed.

Claim 1 recites a surface-mounted electronic component module comprising, among other features, a bonding wire connecting the connection terminal of the one of the plurality of electronic component devices with another of the plurality of electronic component devices or with one of the wiring patterns formed on the one side of the wiring substrate, the bonding wire having a predetermined inductance as an electric circuit element in connection with the electronic component device, to which one terminal of the bonding wire is connected.

It is respectfully submitted that the prior art fails to disclose or suggest at least the above-mentioned features of the Applicants' invention.

In making the rejection, the Office Action characterized Huang as allegedly disclosing "at least one of the wire bondings connecting the connection terminal of the electronic component device, has a predetermined inductance ... as a circuit element,"

and further cited Figure 1, element 23 of the reference. In addition, the Office Action noted that “any circuit element including [a] wire can have a predetermined inductance.

The Applicants respectfully disagree with the Office Action’s position.

Applicants submit that Huang fails to disclose or suggest each and every element recited in claim 1 of the present application. In particular, it is submitted that Huang fails to show at least a bonding wire having a predetermined inductance. For instance, Huang fails to indicate any bonding wire which has a predetermined inductance as an electric circuit element in connection with an electronic component device, to which one terminal of the bonding wire is connected. It is further submitted that unless the inductance is considered as an electric circuit element in connection with a certain electronic component device, the inductance is not an element of the invention.

In contrast, the present invention claims, in part, that the bonding wire, which has a predetermined inductance as an electric circuit element in connection with an electronic component device, to which one terminal of the bonding wire is connected. For example, in the subject matter of claim 5, the bonding wire has a predetermined inductance as an electric circuit element to improve a frequency band characteristic of the surface acoustic wave filter, in which a ripple can be reduced, as shown in Fig. 8.

Moreover, in order to qualify as prior art under 35 U.S.C. §102, a single prior art reference must teach, i.e., identically describe, each feature of a rejected claim. As explained above, Huang fails to disclose or suggest each and every feature of claim 1, and therefore Huang fails to anticipate claim 1. Hence, Applicants respectfully submit that claim 1 is allowable.

Accordingly, Applicants respectfully request withdrawal of the rejection.

Rejection of Claims 3-4 Under 35 U.S.C. § 103(a)

Claims 3-4 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Huang in view of Fujimoto (U.S. Patent No. 6,777,819). Claim 4 has been canceled. To the extent it is still relevant, this rejection is respectfully traversed.

Huang is discussed above. Fujimoto is relied upon for allegedly showing the features recited in claims 3 and 4.

As claim 3 depends from claim 1, Applicants submit that claim 4 incorporates the patentable aspects therein, and is therefore allowable for at least the reasons set forth above with respect to the independent claim, as well as for the additional subject matter recited therein.

Accordingly, Applicants respectfully request withdrawal of the rejection.

Rejection of Claim 5 Under 35 U.S.C. § 103(a)

Claim 5 was rejected under 35 U.S.C. § 103(a) as being unpatentable over Yamada (U.S. Patent No. 6,784,765) in view of Huang. Claim 5 has been amended. To the extent it is still relevant, this rejection is respectfully traversed.

Claim 5 recites a surface-mounted electronic component module comprising, among other features, a bonding wire having one terminal connected to the surface acoustic wave filter and the other terminal connected to the connection terminal of the semiconductor chip the bonding wire having a predetermined inductance as an electric circuit element to improve a frequency band characteristic of the surface acoustic wave filter.

It is respectfully submitted that the prior art fails to disclose or suggest at least the above-mentioned features of the Applicants' invention.

Yamada merely discloses a multilayer ceramic device. Huang is relied upon for allegedly teaching “a semiconductor device (Fig. 1, element 21) that is mounted face up the one side of the wiring substrate and that the connection terminal of the semiconductor chip is connected to the wiring pattern by wire bonding (Fig. 1, element 23).

The Applicants respectfully disagree. Huang is discussed above where it is submitted that Huang fails to disclose or suggest at least the feature of “a bonding wire having one terminal connected to the surface acoustic wave filter and the other terminal connected to the connection terminal of the semiconductor chip the bonding wire having a predetermined inductance as an electric circuit element to improve a frequency band characteristic of the surface acoustic wave filter.”

Therefore, it is submitted that neither Yamada nor Huang, taken alone or in combination, disclose or suggest each and every element recited in claim 5 of the present application, and thus claim 5 is allowable.

Accordingly, Applicants respectfully request withdrawal of the rejection.

Rejection of Claim 7 Under 35 U.S.C. § 103(a)

Claim 7 was rejected under 35 U.S.C. § 103(a) as being unpatentable over Yamada and Huang in view of Fujimoto. Claim 7 has been amended. To the extent it is still relevant, this rejection is respectfully traversed.

As claim 7 depends from claim 5, Applicants submit that claim 7 incorporates the patentable aspects therein, and is therefore allowable for at least the reasons set forth above with respect to the independent claim, as well as for the additional subject matter recited therein.

Accordingly, Applicants respectfully request withdrawal of the rejection.

Conclusion

In view of the above, the Applicants respectfully request the allowance of claims 1, 3, 5 and 7 and the prompt issuance of a Notice of Allowability.

Should the Examiner believe anything further is desirable in order to place this application in better condition for allowance, the Examiner is requested to contact the undersigned at the telephone number listed below.

In the event this paper is not considered to be timely filed, the Applicants respectfully petition for an appropriate extension of time. Any fees for such an extension, together with any additional fees that may be due with respect to this paper, may be charged to counsel's Deposit Account No. 01-2300, referencing Attorney Docket No. 108066-00087.

Respectfully submitted,


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Enclosure: Petition for Extension of Time (one month)